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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	10/066,023	Confirmation No.	4878
First Inventor	Allen K. Lam	Filing Date	01/30/02
Tech. Center/ Art Unit	2826	Examiner	Alexander O. Williams
Title:	Package For Semiconductor Die Containing Symmetrical Lead And Heat Sink		
Docket No.:	AAT009-2D US	Customer No.:	34036

Santa Clara, California  
November 20, 2003

COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

In response to Office Action dated June 20, 2003, please amend the above-identified application as follows.

**An Amendment to the Title** is set forth on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims, which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.

Appl. No. 10/066,023  
Amdt dated November 20, 2003  
Rply to Office Action of June 20, 2003

**Amendment to the Title:**

Please amend the title to read as follows:

C'

"Package For Semiconductor Die Containing Symmetrical Lead And Heat Sink"

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